

**Advanced DRAM Technology Agreement  
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\*\*\*\*\*For immediate release January 17, 2000

**MULTIPLE COMPANIES AGREE TO DEVELOP  
ADVANCED DRAM TECHNOLOGY**

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DATELINE - Hyundai Electronics, Infineon Technologies, Intel Corporation, Micron Technology, Inc., NEC Corporation, and Samsung Electronics, today announced they will cooperatively develop a high-performance advanced DRAM technology targeted for potential applications in 2003 and beyond. Developers anticipate that this DRAM technology will be suitable for multiple cost-effective computing platforms of the future. Under the terms of the agreement, the developers will work together and with industry participants to develop the architecture, electrical and physical design, and related infrastructure for this advanced DRAM technology. The developers will enable the adoption of this advanced DRAM technology by providing application, design and other information needed to develop future chipsets, platforms, and other elements critical to bringing the future memory technology to market.

This advanced DRAM technology will be industry developed. Interested companies can access design information and will be able to provide input in the development process by entering into a participant's agreement during the development process, specifications will be provided to participants for review and feedback. Final specifications will be made available to all interested parties.

This cooperative development effort between developers and participants will help ensure that the DRAM roadmap is consistent with microprocessor and system architecture evolution in a variety of future systems.

For the Developers, please see the attached sheet.

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